



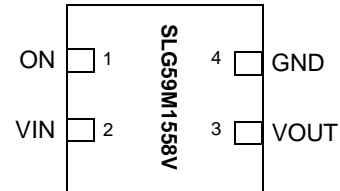
General Description

The SLG59M1558V is designed for load switching applications with ultra low quiescent current. The part comes with one 28.5 mΩ 1.0 A rated P-channel MOSFET controlled by a single ON control pin. The product is packaged in an ultra-small 1.0 x 1.0 mm package.

Features

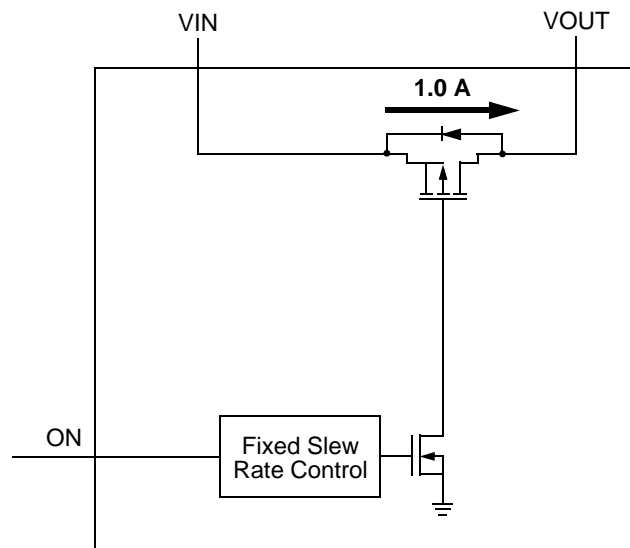
- One 1.0 A MOSFET
- Ultra Low Quiescent Current
- Low RDSON
 - 28.5 mΩ @ 5.0 V
 - 36.4 mΩ @ 3.3 V
 - 44.3 mΩ @ 2.5 V
 - 60.8 mΩ @ 1.8 V
 - 77.6 mΩ @ 1.5 V
- $V_{IN} = 1.5 V$ to 5.5 V
- Pb-Free / Halogen-Free / RoHS compliant
- STDFN 4L, 1.0 x 1.0 x 0.55 mm

Pin Configuration



4-pin STDFN
(Top View)

Block Diagram





Pin Description

| Pin # | Pin Name | Type | Pin Description |
|-------|----------|--------|---------------------|
| 1 | ON | Input | Turns on MOSFET. |
| 2 | VIN | MOSFET | Power MOSFET input |
| 3 | VOUT | MOSFET | Power MOSFET output |
| 4 | GND | GND | Ground |

Ordering Information

| Part Number | Type | Production Flow |
|---------------|--------------------------|-----------------------------|
| SLG59M1558V | STDFN 4L | Industrial, -40 °C to 85 °C |
| SLG59M1558VTR | STDFN 4L (Tape and Reel) | Industrial, -40 °C to 85 °C |



Absolute Maximum Ratings

| Parameter | Description | Conditions | Min. | Typ. | Max. | Unit |
|----------------------------|-----------------------------------|--|------|------|------|------|
| V _{DD} | Power Supply | | -- | -- | 6 | V |
| T _S | Storage Temperature | | -65 | -- | 140 | °C |
| ESD _{HBM} | ESD Protection | Human Body Model | 2000 | -- | -- | V |
| W _{DIS} | Package Power Dissipation | | -- | -- | 0.5 | W |
| MOSFET I _{DS(PK)} | Peak Current from Drain to Source | For no more than 1 ms with 1% duty cycle | -- | -- | 1.5 | A |

Note: Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Electrical Characteristics

T_A = -40 °C to 85 °C (unless otherwise stated)

| Parameter | Description | Conditions | Min. | Typ. | Max. | Unit |
|-----------------------|--|--|------|------|------|------|
| V _{IN} | Power Supply Voltage | -40 °C to 85 °C | 1.5 | -- | 5.5 | V |
| I _{DD} | Power Supply Current (PIN 2) | when OFF, V _{IN} = 5.5 V, No load | -- | 0.02 | 1 | μA |
| | | when ON = V _{IN} , No load | -- | 0.05 | 0.5 | μA |
| I _{ON_LKG} | ON Pin Input Leakage | | -- | -- | 0.1 | μA |
| R _{DS(ON)} | Static Drain to Source ON Resistance @ T _A 25°C | @ 5.5 V | -- | 28.5 | 32.0 | mΩ |
| | | @ 3.3 V | -- | 36.4 | 40.0 | mΩ |
| | | @ 2.5 V | -- | 44.3 | 49.0 | mΩ |
| | | @ 1.8 V | -- | 60.8 | 65.0 | mΩ |
| | | @ 1.5 V | -- | 77.6 | 82.0 | mΩ |
| R _{DS(ON)} | Static Drain to Source ON Resistance @ T _A 85°C | @ 5.5 V | -- | 34.0 | 36.0 | mΩ |
| | | @ 3.3 V | -- | 43.8 | 46.0 | mΩ |
| | | @ 2.5 V | -- | 53.3 | 56.0 | mΩ |
| | | @ 1.8 V | -- | 72.2 | 76.0 | mΩ |
| | | @ 1.5 V | -- | 90.7 | 94.0 | mΩ |
| IDS | Operating Current | V _{IN} = 1.5 V to 5.5 V | -- | -- | 1.0 | A |
| T _{ON_Delay} | ON pin Delay Time | 50% ON to Ramp Begin V _{IN} = 5 V, V _{OUT_Cap} = 0.1 μF, R _L = 10 Ω | 10 | 15 | 27 | μs |
| | | 50% ON to Ramp Begin V _{IN} = 3.3 V, V _{OUT_Cap} = 0.1 μF, R _L = 10 Ω | 17 | 31 | 40 | μs |
| | | 50% ON to Ramp Begin V _{IN} = 1.5 V, V _{OUT_Cap} = 0.1 μF, R _L = 10 Ω | 44 | 69 | 96 | μs |
| T _{Total_ON} | Total Turn On Time | 50% ON to 90% V _{OUT} V _{IN} = 5 V, V _{OUT_Cap} = 0.1 μF, R _L = 10 Ω | 114 | 122 | 134 | μs |
| | | 50% ON to 90% V _{OUT} V _{IN} = 3.3 V, V _{OUT_Cap} = 0.1 μF, R _L = 10 Ω | 146 | 156 | 176 | μs |
| | | 50% ON to 90% V _{OUT} V _{IN} = 1.5 V, V _{OUT_Cap} = 0.1 μF, R _L = 10 Ω | 292 | 332 | 399 | μs |

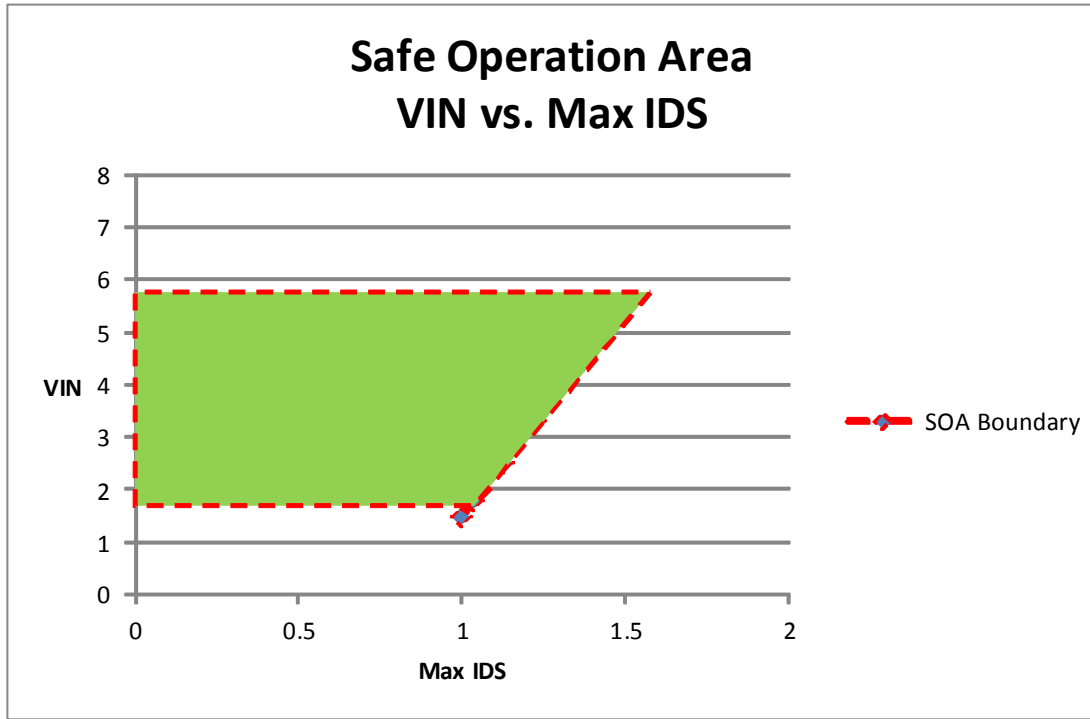


T_A = -40 °C to 85 °C (unless otherwise stated)

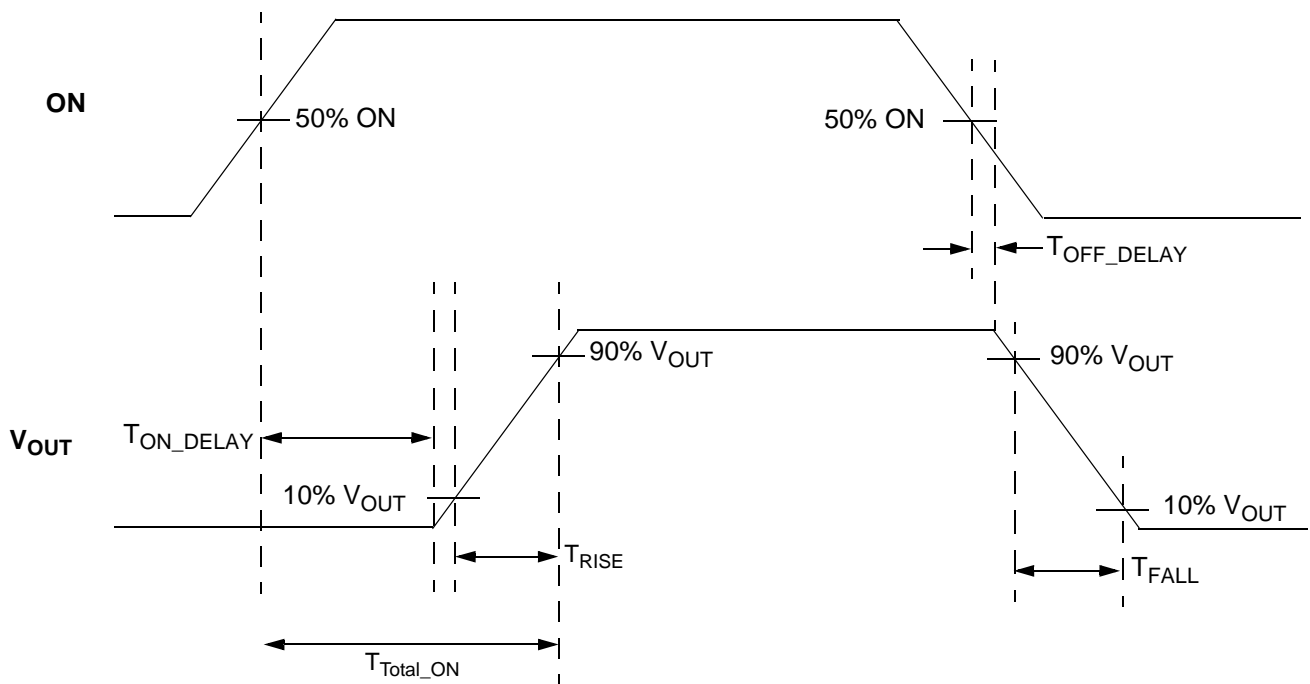
| Parameter | Description | Conditions | Min. | Typ. | Max. | Unit |
|------------------------|-----------------------------|--|------|------|-----------------|------|
| T _{RISE} | Rise Time | 10% VOUT to 90% VOUT V _{IN} = 5.0 V, VOUT_Cap = 0.1 μF, R _L = 10 Ω | 92 | 97 | 107 | μs |
| | | 10% VOUT to 90% VOUT V _{IN} = 3.3 V, VOUT_Cap = 0.1 μF, R _L = 10 Ω | 116 | 120 | 131 | μs |
| | | 10% VOUT to 90% VOUT V _{IN} = 1.5 V, VOUT_Cap = 0.1 μF, R _L = 10 Ω | 228 | 253 | 296 | μs |
| ON_V _{IH} | Initial Turn On Voltage | | 0.85 | -- | V _{IN} | V |
| ON_V _{IL} | Low Input Voltage on ON pin | | -0.3 | 0 | 0.3 | V |
| T _{Delay_OFF} | OFF Delay Time | 50% ON to V _{OUT} Fall, V _{IN} = 5 V, R _L = 10 Ω | 6.2 | 6.5 | 7.0 | μs |



VIN vs. Max IDS, Safe Operation Area



T_{Total_ON}, T_{ON_Delay} and Slew Rate Measurement

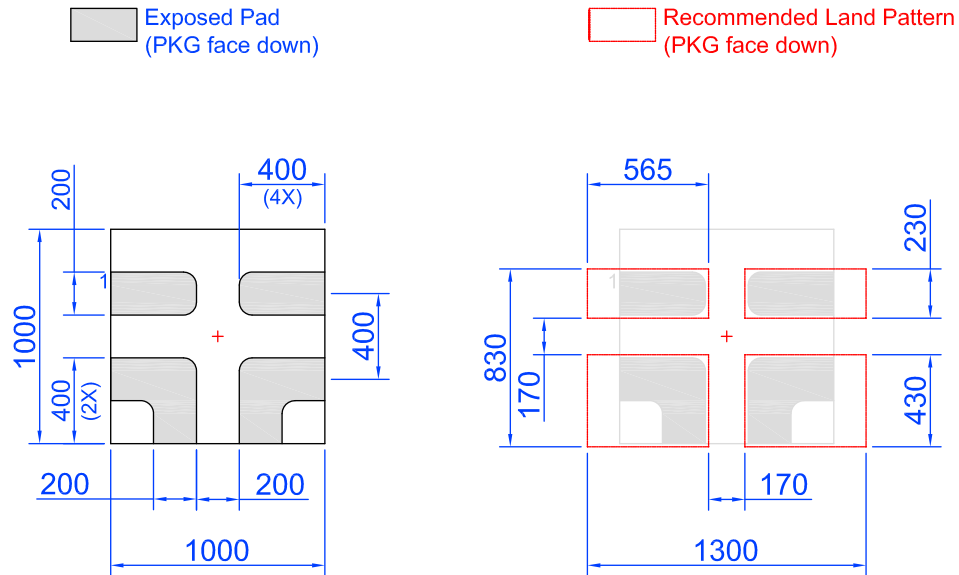




SLG59M1558V Power-Up/Power-Down Sequence Considerations

A nominal power-up sequence is to apply VIN and toggle the ON pin LOW-to-HIGH after VIN is at least 90% of its final value. A nominal power-down sequence is the power-up sequence in reverse order. If VIN ramp is too fast, a voltage glitch may appear on the output pin at VOUT. To prevent glitches at the output, it is recommended to connect at least 0.1uF capacitor from the VOUT pin to GND and to keep the VIN ramp time less than 2 ms.

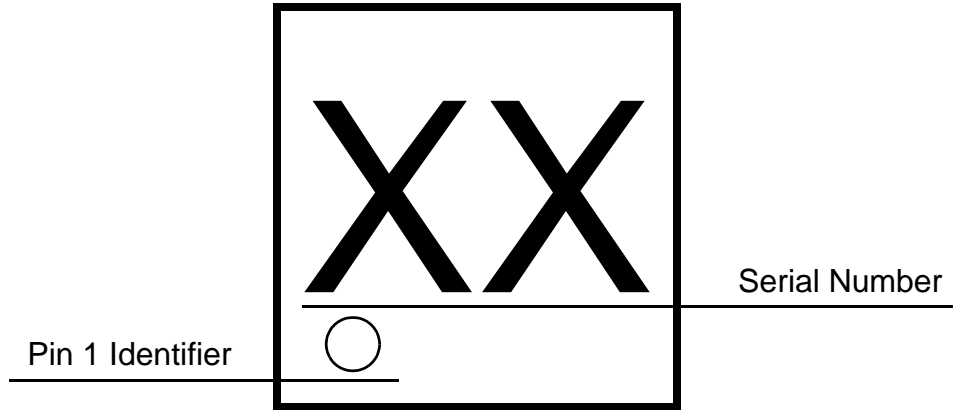
SLG59M1558V Layout Suggestion



Note: All dimensions shown in micrometers (μm)



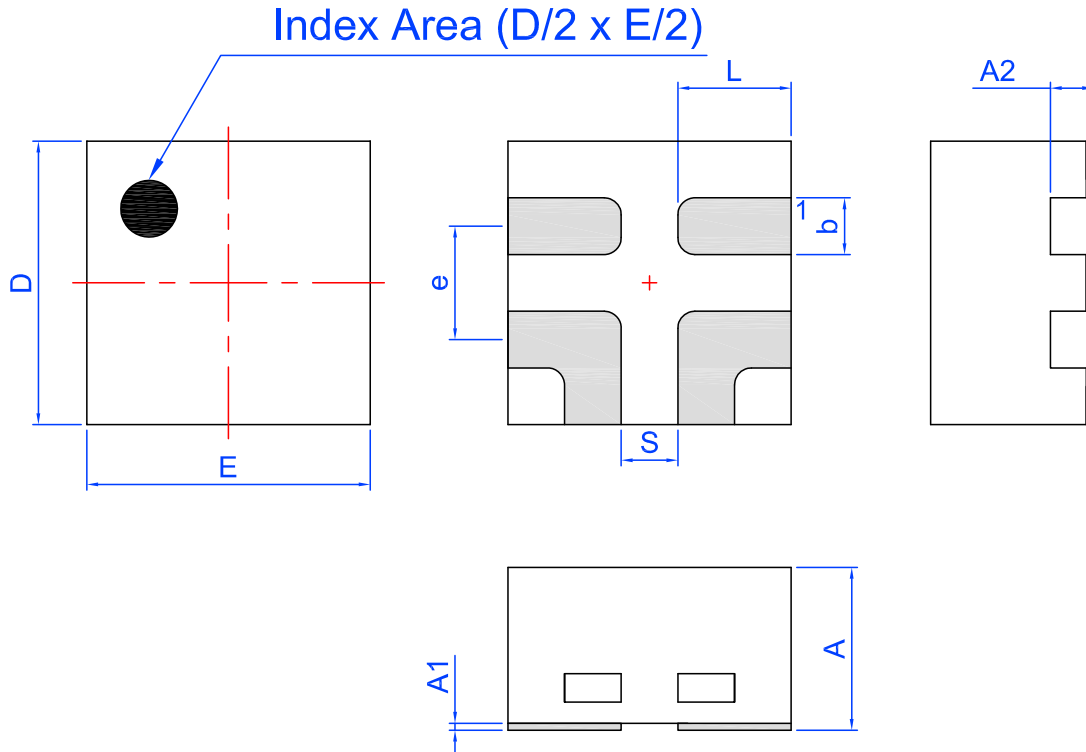
Package Top Marking System Definition





Package Drawing and Dimensions

4 Lead STDFN Package 1.0 x 1.0 mm



Unit: mm

| Symbol | Min | Nom. | Max | Symbol | Min | Nom. | Max |
|--------|----------|------|-------|--------|---------|------|------|
| A | 0.50 | 0.55 | 0.60 | D | 0.95 | 1.00 | 1.05 |
| A1 | 0.005 | - | 0.060 | E | 0.95 | 1.00 | 1.05 |
| A2 | 0.10 | 0.15 | 0.20 | L | 0.35 | 0.40 | 0.45 |
| b | 0.15 | 0.20 | 0.25 | S | 0.2 REF | | |
| e | 0.40 BSC | | | | | | |

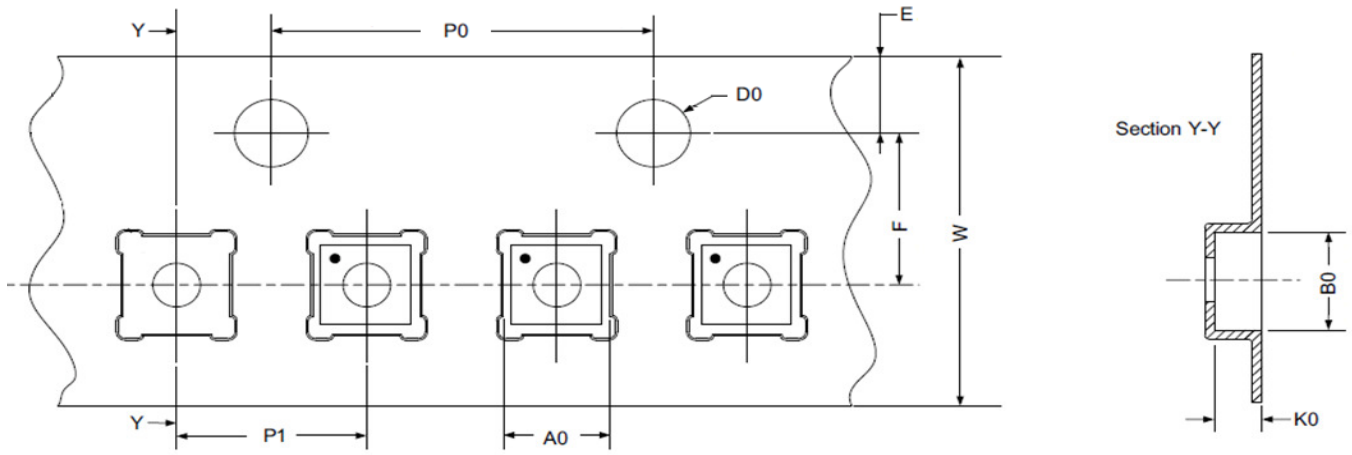


Tape and Reel Specifications

| Package Type | # of Pins | Nominal Package Size [mm] | Max Units | | Reel & Hub Size [mm] | Leader (min) | | Trailer (min) | | Tape Width [mm] | Part Pitch [mm] |
|---------------------------------------|-----------|---------------------------|-----------|---------|----------------------|--------------|-------------|---------------|-------------|-----------------|-----------------|
| | | | per Reel | per Box | | Pockets | Length [mm] | Pockets | Length [mm] | | |
| STDFN 4L 1x1mm 0.4P FC Green | 4 | 1.0 x 1.0 x 0.55 | 8000 | 8000 | 178 / 60 | 200 | 400 | 200 | 400 | 8 | 2 |

Carrier Tape Drawing and Dimensions

| Package Type | Pocket BTM Length | Pocket BTM Width | Pocket Depth | Index Hole Pitch | Pocket Pitch | Index Hole Diameter | Index Hole to Tape Edge | Index Hole to Pocket Center | Tape Width |
|------------------------------------|-------------------|------------------|--------------|------------------|--------------|---------------------|-------------------------|-----------------------------|------------|
| | A0 | B0 | K0 | P0 | P1 | D0 | E | F | W |
| STDFN 4L 1x1mm 0.4P FC Green | 1.16 | 1.16 | 0.63 | 4 | 2 | 1.5 | 1.75 | 3.5 | 8 |



Refer to EIA-481 specification

Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 0.55 mm³ (nominal). More information can be found at www.jedec.org.



Revision History

| Date | Version | Change |
|-----------|---------|---|
| 6/22/2016 | 1.02 | Added section on Power Up/Down Sequence Considerations Removed IDS_lkg parameter (same as IDD when OFF) Updated Recommended Layout suggestion |
| 9/11/2015 | 1.01 | Updatd IDD and Tdelay_ON |